

NEC**MOS FIELD EFFECT TRANSISTOR**
 μ PA621TT**N-CHANNEL MOS FIELD EFFECT TRANSISTOR**
FOR SWITCHING**DESCRIPTION**

The μ PA621TT is a switching device, which can be driven directly by a 2.5 V power source.

This device features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

FEATURES

- 2.5 V drive available
- Low on-state resistance
 $R_{DS(on)1} = 50 \text{ m}\Omega \text{ MAX. (} V_{GS} = 4.5 \text{ V, } I_D = 2.5 \text{ A)}$
 $R_{DS(on)2} = 53 \text{ m}\Omega \text{ MAX. (} V_{GS} = 4.0 \text{ V, } I_D = 2.5 \text{ A)}$
 $R_{DS(on)3} = 79 \text{ m}\Omega \text{ MAX. (} V_{GS} = 2.5 \text{ V, } I_D = 2.5 \text{ A)}$

ORDERING INFORMATION

PART NUMBER	PACKAGE
μ PA621TT	6pinWSOF (1620)

Marking: WB

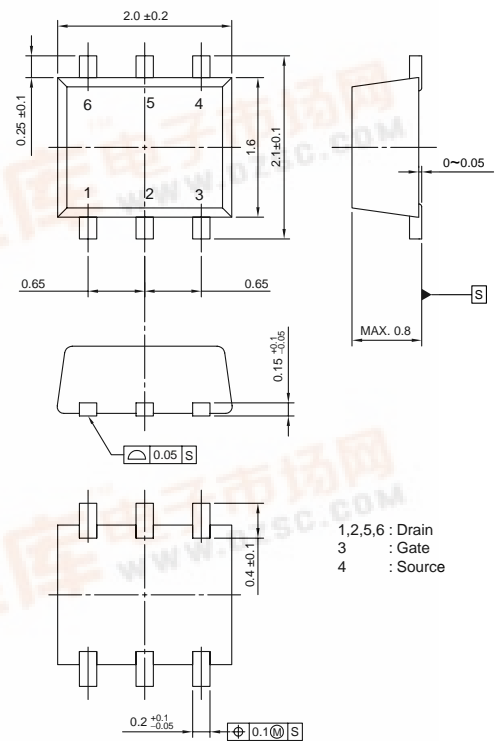
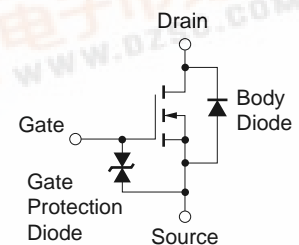
ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Drain to Source Voltage (V _{GS} = 0 V)	V _{DSS}	20	V
Gate to Source Voltage (V _{DS} = 0 V)	V _{GSS}	±12	V
Drain Current (DC) (T _A = 25°C)	I _{D(DC)}	±5.0	A
Drain Current (pulse) ^{Note1}	I _{D(pulse)}	±20	A
Total Power Dissipation	P _{T1}	0.2	W
Total Power Dissipation ^{Note2}	P _{T2}	1.4	W
Channel Temperature	T _{ch}	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Notes 1. PW ≤ 10 μs, Duty Cycle ≤ 1%

2. Mounted on FR-4 board, t ≤ 5 sec.

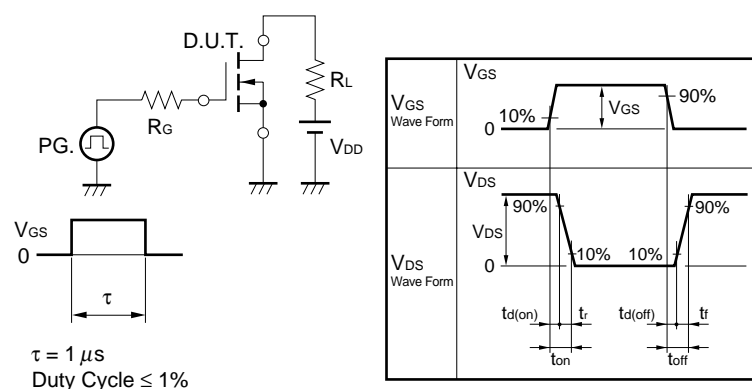
Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

PACKAGE DRAWING (Unit: mm)**EQUIVALENT CIRCUIT**

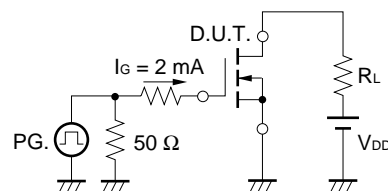
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			10	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±12 V, V _{DS} = 0 V			±10	μA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1.0 mA	0.5	1.0	1.5	V
Forward Transfer Admittance	y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	1.0	4.8		S
Drain to Source On-state Resistance	R _{DS(on)1}	V _{GS} = 4.5 V, I _D = 2.5 A		40	50	mΩ
	R _{DS(on)2}	V _{GS} = 4.0 V, I _D = 2.5 A		42	53	mΩ
	R _{DS(on)3}	V _{GS} = 2.5 V, I _D = 2.5 A		59	79	mΩ
Input Capacitance	C _{iss}	V _{DS} = 10 V		270		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V		80		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0 MHz		60		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 10 V, I _D = 2.5 A		30		ns
Rise Time	t _r	V _{GS} = 4.0 V		200		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		120		ns
Fall Time	t _f			160		ns
Total Gate Charge	Q _G	V _{DD} = 16 V		3.3		nC
Gate to Source Charge	Q _{GS}	V _{GS} = 4.0 V		0.7		nC
Gate to Drain Charge	Q _{GD}	I _D = 5.0 A		1.8		nC
Body Diode Forward Voltage	V _{F(S-D)}	I _F = 5.0 A, V _{GS} = 0 V		0.90		V

TEST CIRCUIT 1 SWITCHING TIME

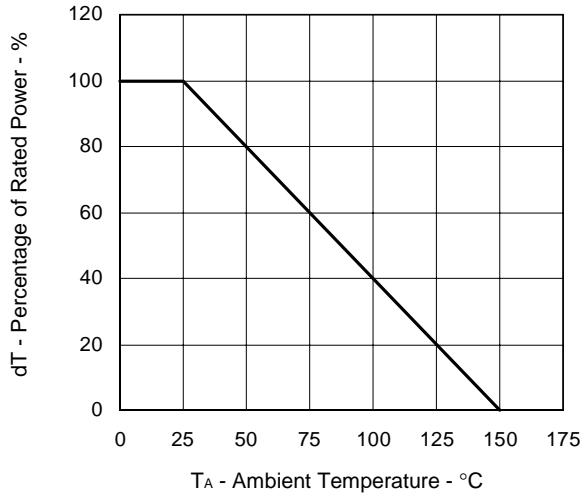


TEST CIRCUIT 2 GATE CHARGE

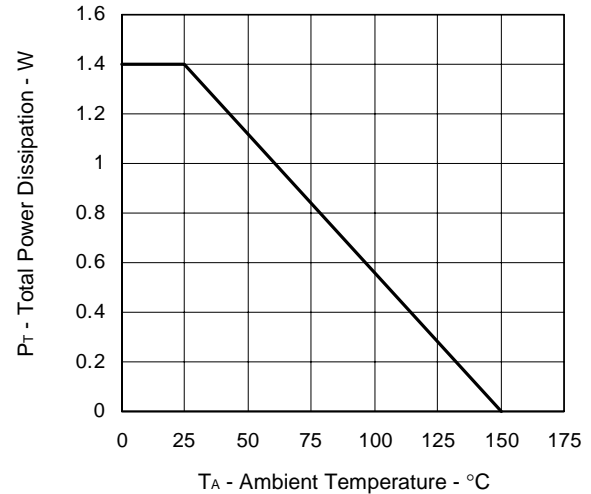


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

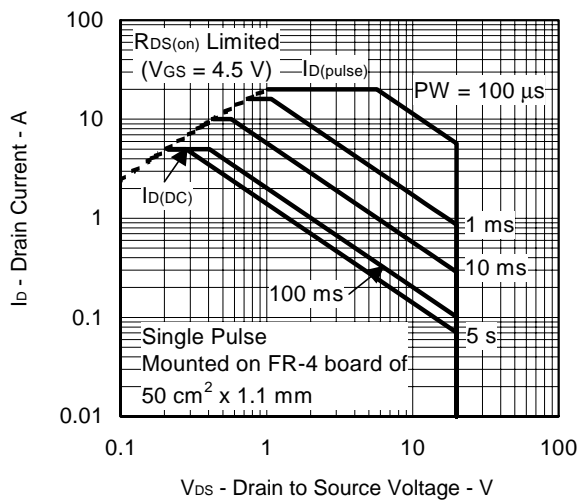
DERATING FACTOR OF FORWARD BIAS
SAFE OPERATING AREA



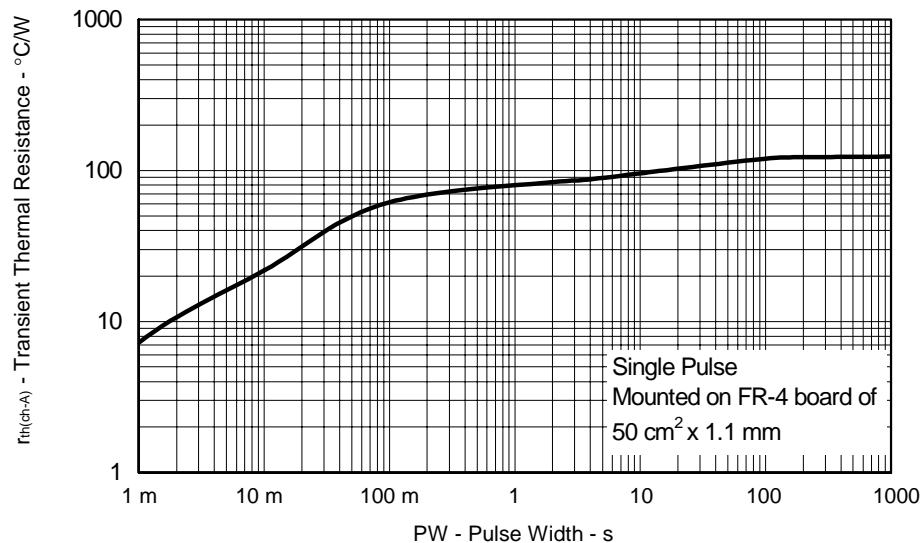
TOTAL POWER DISSIPATION vs.
AMBIENT TEMPERATURE



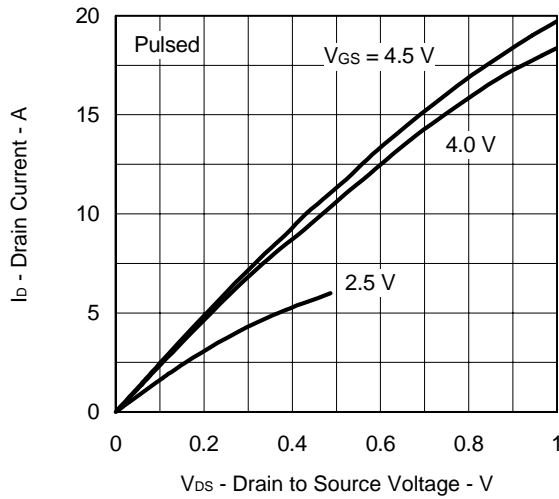
FORWARD BIAS SAFE OPERATING AREA



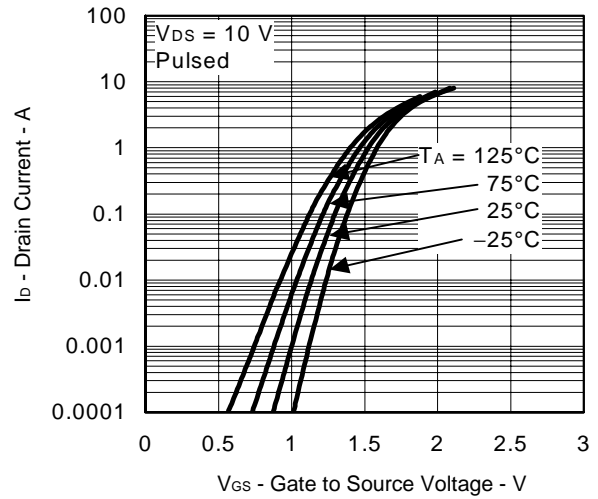
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



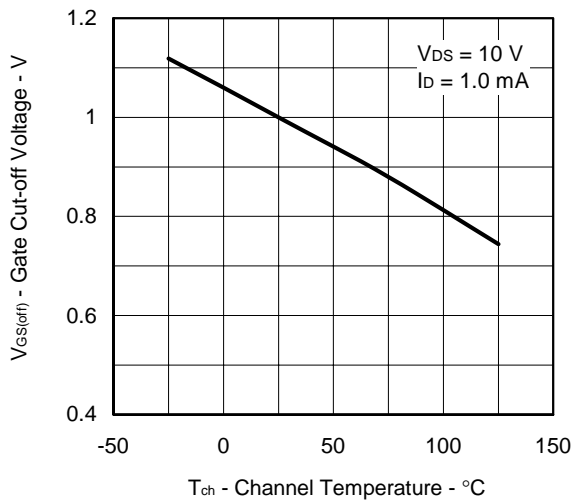
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



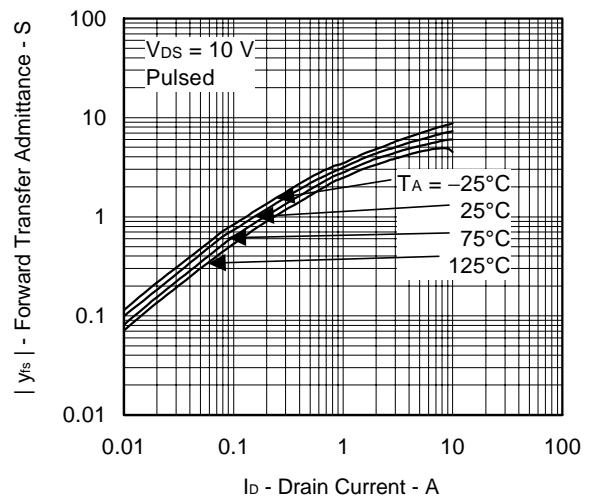
FORWARD TRANSFER CHARACTERISTICS



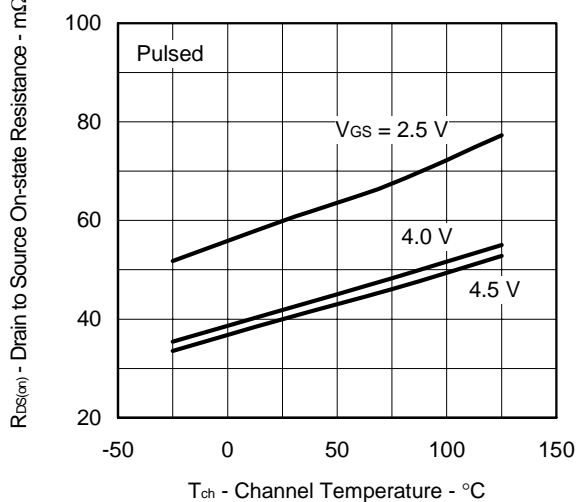
GATE CUT-OFF VOLTAGE vs.
CHANNEL TEMPERATURE



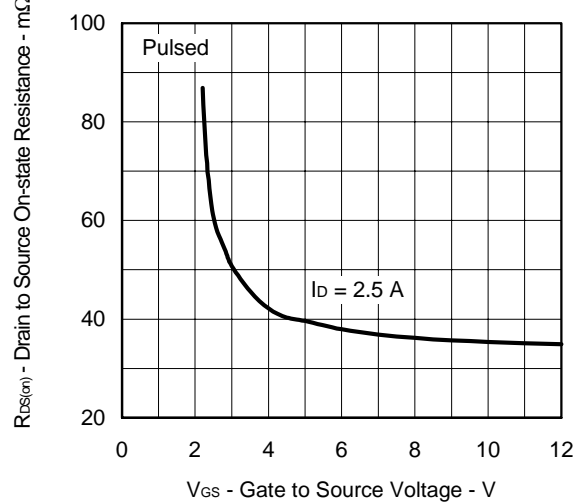
FORWARD TRANSFER ADMITTANCE vs.
DRAIN CURRENT



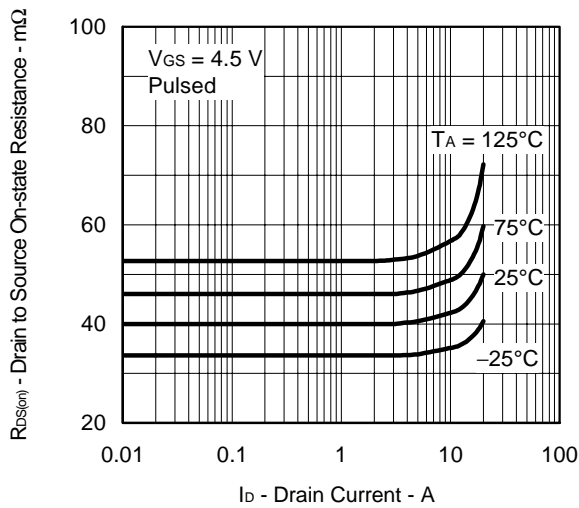
DRAIN TO SOURCE ON-STATE RESISTANCE vs.
CHANNEL TEMPERATURE



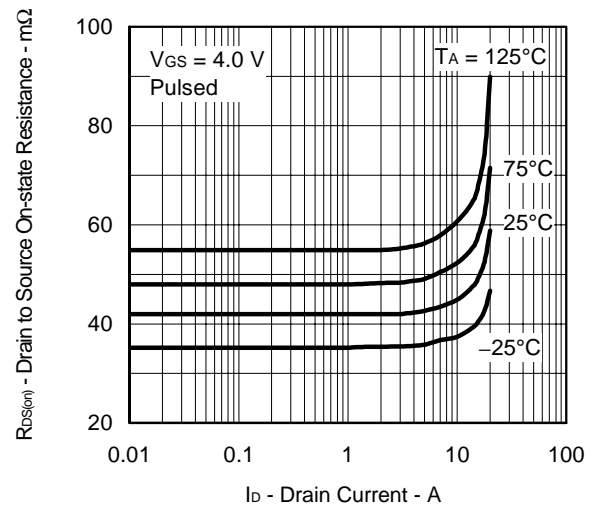
DRAIN TO SOURCE ON-STATE RESISTANCE vs.
GATE TO SOURCE VOLTAGE



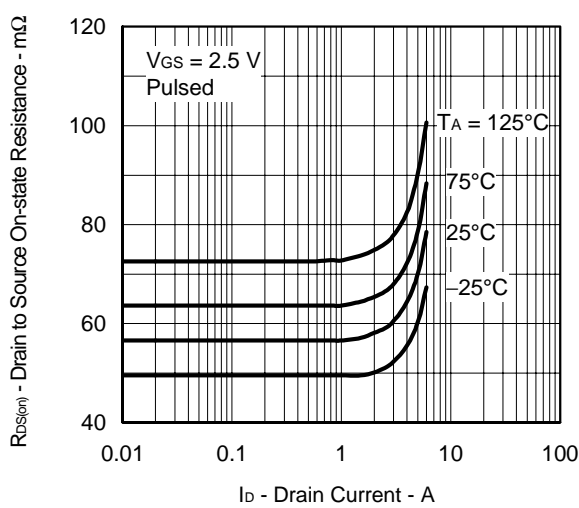
DRAIN TO SOURCE ON-STATE
RESISTANCE vs. DRAIN CURRENT



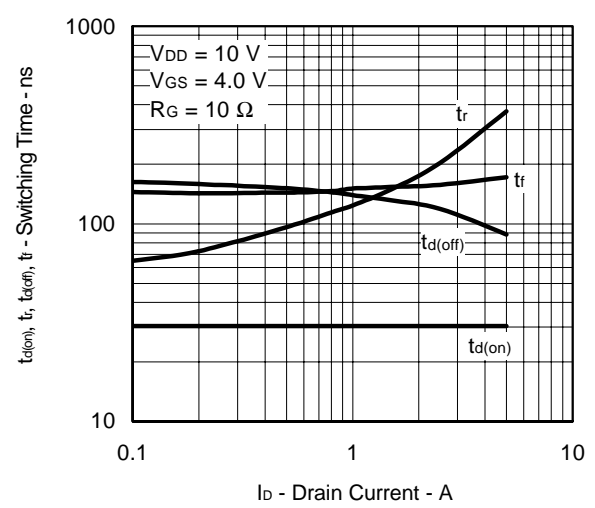
DRAIN TO SOURCE ON-STATE
RESISTANCE vs. DRAIN CURRENT



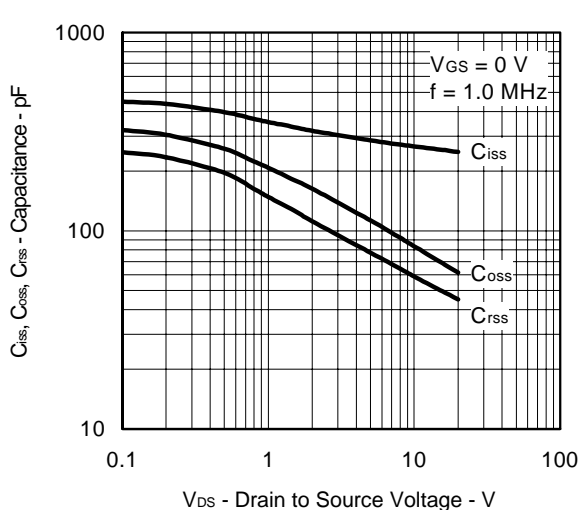
DRAIN TO SOURCE ON-STATE
RESISTANCE vs. DRAIN CURRENT



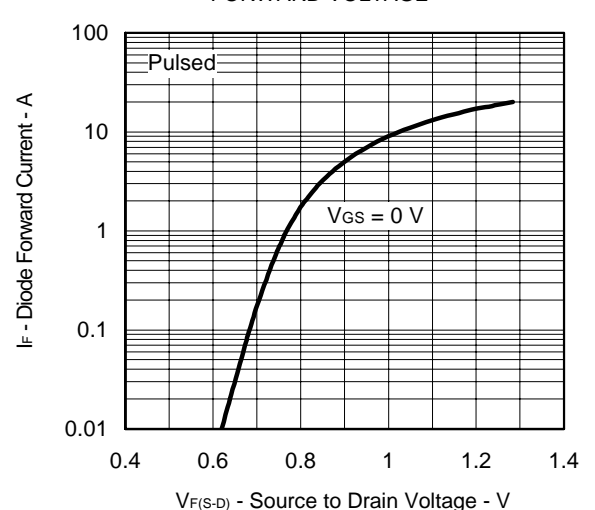
SWITCHING CHARACTERISTICS



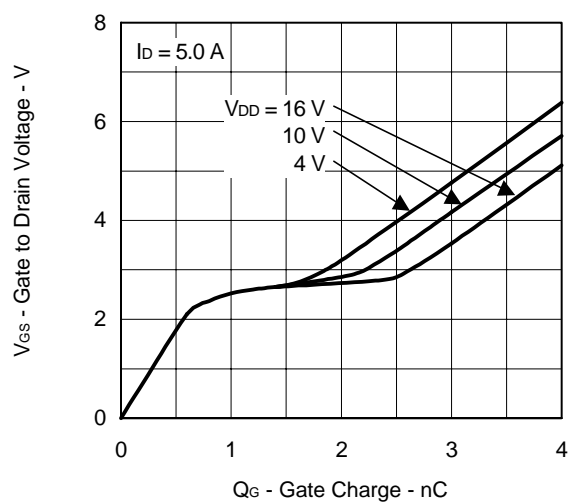
CAPACITANCE vs.
DRAIN TO SOURCE VOLTAGE



SOURCE TO DRAIN DIODE
FORWARD VOLTAGE



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



[MEMO]

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